



Material Content Data Sheet



Sales Product Name		6EDL04I06NT		Issued		29. August 2013			
MA#		MA001033150							
Package		PG-DSO-28-17		Weight*		814.77 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.034	0.37	0.37	3724	3724	
leadframe	non noble metal	zinc	7440-66-6	0.288	0.04		353		
	inorganic material	phosphorus	7723-14-0	0.072	0.01		88		
	non noble metal	iron	7439-89-6	5.754	0.71		7062		
	non noble metal	copper	7440-50-8	233.637	28.68	29.44	286751	294254	
wire	noble metal	gold	7440-57-5	0.995	0.12	0.12	1221	1221	
encapsulation	organic material	carbon black	1333-86-4	1.693	0.21		2077		
	plastics	epoxy resin	-	71.650	8.79		87939		
	inorganic material	silicondioxide	60676-86-0	490.831	60.24	69.24	602415	692431	
leadfinish	non noble metal	tin	7440-31-5	4.913	0.60	0.60	6030	6030	
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	832	832	
glue	plastics	epoxy resin	-	0.246	0.03		302		
	noble metal	silver	7440-22-4	0.983	0.12	0.15	1206	1508	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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